

Serial No.: 10/693,217  
Group Art Unit: 2811

#### AMENDMENTS TO THE SPECIFICATION

- Please amend the Cross-Reference to Related Application(s) section which begins on page 1, line 2, as follows:

#### CROSS-REFERENCE TO RELATED APPLICATION(S)

This is a Divisional of co-pending application serial number 09/640,534 filed 8/17/2000, now U.S. Patent No. 6,660,565 B1, the entire disclosure of which is incorporated herein by reference.

- Please amend the Description of the Preferred Embodiments section of the Specification, which begins on page 5, line 13, as follows:

The total package that has been created in this manner contains the IC chip 30 with its contact balls 18, a mold compound 34 that surrounds the IC chip 30 while providing the underfill for the IC chip 30, a heatsink 16 and a substrate 12 with its contact balls 20. Substrate 12 is provided with a network of interconnect lines that interconnects the substrate upper surface contact points with the substrate lower surface contact points, this network to be contained in one or more planes within the substrate. Cavity 32 is created by creating four planer spacers that separate the heatsink from the substrate by a measurable amount, this amount to be selected such that contact points of the IC device make contact with the substrate upper surface contact points while ~~a~~ an upper surface of the IC device ~~make~~ makes contact with the heatsink.